

5-103916-2 ✓ ACTIVE

AMPMODU | AMPMODU System 50

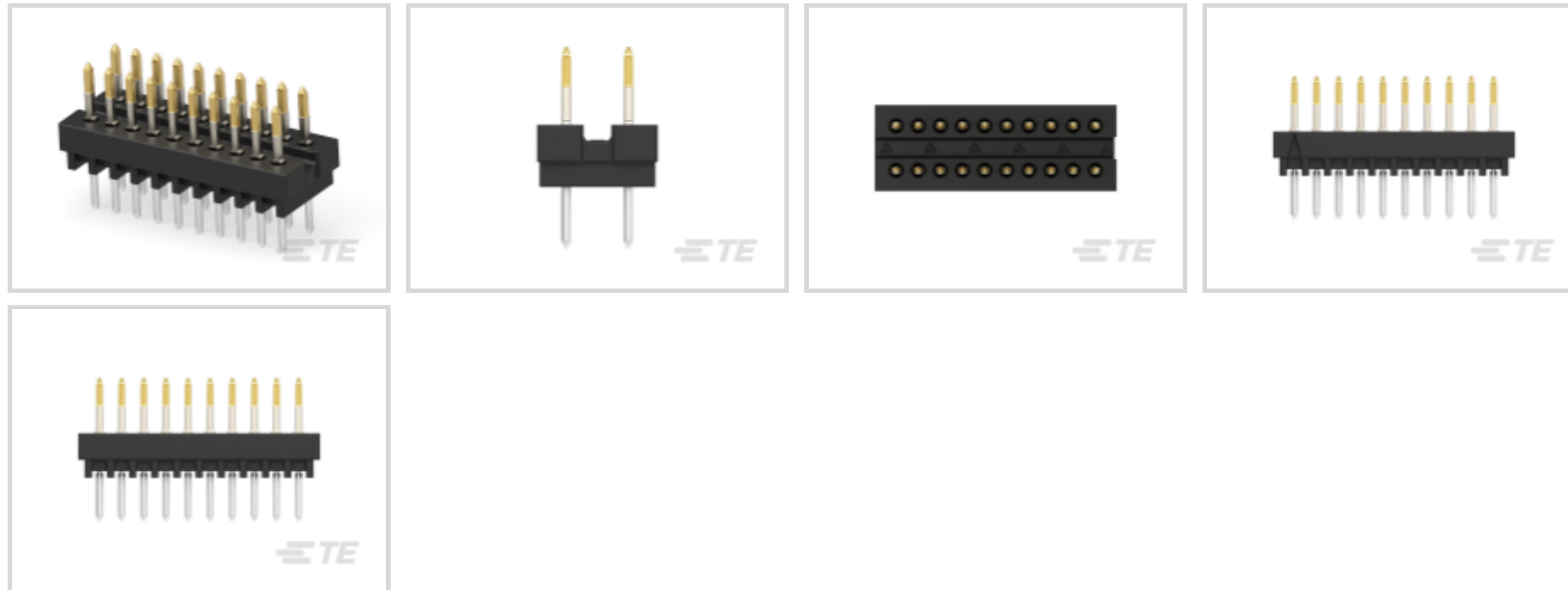
TE Internal #: 5-103916-2

PCB Mount Header, Vertical, Board-to-Board, 20 Position, 1.27 mm
[.05 in] Centerline, Unshrouded, Gold, Through Hole - Solder,
AMPMODU System 50

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **20**

Number of Rows: **2**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| PCB Connector Assembly Type | PCB Mount Header |
| Connector System | Board-to-Board |
| Header Type | Unshrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|----------------------------------|--------------|
| Connector Contact Load Condition | Fully Loaded |
| PCB Mount Orientation | Vertical |
| Number of Positions | 20 |
| Number of Rows | 2 |
| Board-to-Board Configuration | Parallel |

Electrical Characteristics

| | |
|---------------------------------------|---------|
| Dielectric Withstanding Voltage (Max) | 500 VAC |
| Insulation Resistance | 5000 MΩ |



| | |
|-------------------|--------|
| Operating Voltage | 30 VAC |
|-------------------|--------|

Body Features

| | |
|-----------------------|-------|
| Primary Product Color | Black |
|-----------------------|-------|

Contact Features

| | |
|------------------------------|-----------------|
| Mating Square Post Dimension | .38 mm[.015 in] |
|------------------------------|-----------------|

| | |
|---|---|
| PCB Contact Termination Area Plating Material Thickness | 3.81 – 6.35 μm [150 – 250 μin] |
|---|---|

| | |
|--|-------|
| PCB Contact Termination Area Plating Material Finish | Matte |
|--|-------|

| | |
|----------------------|-------------|
| Contact Shape & Form | Rectangular |
|----------------------|-------------|

| | |
|-------------------------------|--------|
| Contact Underplating Material | Nickel |
|-------------------------------|--------|

| | |
|---|-----|
| PCB Contact Termination Area Plating Material | Tin |
|---|-----|

| | |
|-----------------------|--------------|
| Contact Base Material | Copper Alloy |
|-----------------------|--------------|

| | |
|--------------------------------------|------|
| Contact Mating Area Plating Material | Gold |
|--------------------------------------|------|

| | |
|--|--|
| Contact Mating Area Plating Material Thickness | .76 μm [30 μin] |
|--|--|

| | |
|--------------|-----|
| Contact Type | Pin |
|--------------|-----|

| | |
|------------------------------|-------|
| Contact Current Rating (Max) | 3.6 A |
|------------------------------|-------|

Termination Features

| | |
|--|-----------------|
| Round Termination Post & Tail Diameter | .38 mm[.015 in] |
|--|-----------------|

| | |
|--------------------------------|----------------|
| Termination Post & Tail Length | 2.54 mm[.1 in] |
|--------------------------------|----------------|

| | |
|---|-----------------------|
| Termination Method to Printed Circuit Board | Through Hole - Solder |
|---|-----------------------|

Mechanical Attachment

| | |
|------------------|---------|
| Mating Alignment | Without |
|------------------|---------|

| | |
|---------------------|---------|
| PCB Mount Retention | Without |
|---------------------|---------|

| | |
|---------------------|---------|
| PCB Mount Alignment | Without |
|---------------------|---------|

| | |
|-------------------------|-------------|
| Connector Mounting Type | Board Mount |
|-------------------------|-------------|

Housing Features

| | |
|--------------------|-----------------|
| Centerline (Pitch) | 1.27 mm[.05 in] |
|--------------------|-----------------|

| | |
|------------------|-----|
| Housing Material | LCP |
|------------------|-----|

Dimensions

| | |
|--------------------|----------------|
| Row-to-Row Spacing | 2.54 mm[.1 in] |
|--------------------|----------------|

| | |
|-----------------------------|------------------|
| PCB Thickness (Recommended) | 1.57 mm[.062 in] |
|-----------------------------|------------------|

Usage Conditions

| | |
|----------------------------|------|
| Housing Temperature Rating | High |
|----------------------------|------|



Operating Temperature Range -65 – 105 °C[-85 – 221 °F]

Operation/Application

| | |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Industry Standards

| | |
|------------------------|-----------------------|
| UL Rating | Recognized |
| Agency/Standard | CSA, UL |
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |

Packaging Features

| | |
|--------------------|-----------|
| Packaging Quantity | 100 |
| Packaging Type | Box, Tube |

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Wave solder capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

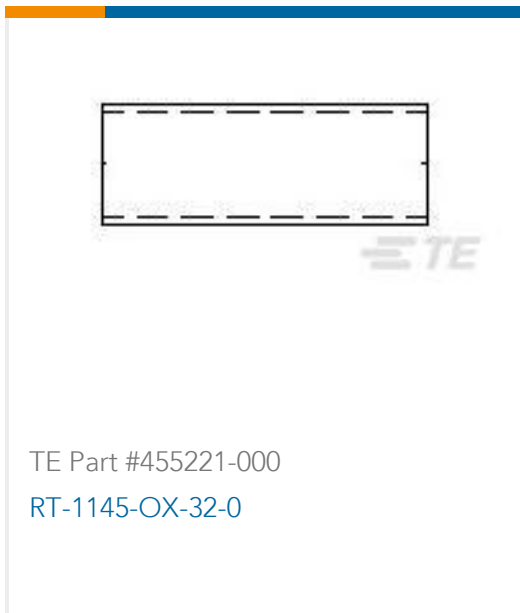
Compatible Parts



Also in the Series | AMPMODU System 50

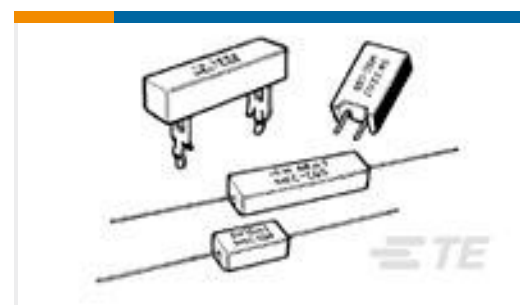


Customers Also Bought





TE Part #2-2176231-0
3522 62R 1% 3W



TE Part #1-1623783-8
SQM7 6K8 5% (METAL FILM)



TE Part #643405-1
05P UMNL PIN HDR ASSY POL NATL



TE Part #4-2176325-9
CRGP 0402 100K 1%



TE Part #5145300-2
SMT CARD RCPT, 8 POS, W/ COVER



TE Part #CONREVSMA001-G
RP-SMA Jack 50 Ohm PCB Through Hole

Documents

Product Drawings

[20 SYS 50 HDR DRST UNSHRD SN](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_5-103916-2_Z.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_5-103916-2_Z.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_5-103916-2_Z.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4](#)

English

Product Specifications

[Application Specification](#)

English

Product Environmental Compliance

[MD_5-103916-2_0323201877_dmtec](#)

5-103916-2

PCB Mount Header, Vertical, Board-to-Board, 20 Position, 1.27 mm [.05 in] Centerline,
Unshrouded, Gold, Through Hole - Solder, AMPMODU System 50



English

[MD_5-103916-2_0323201877_dmtec](#)

English